

## ABSTRACT OF THE DISCLOSURE

A multiple-conditioning member device for chemical mechanical planarization conditioning is described. The multiple conditioning members may be used in a chemical mechanical planarization apparatus which further includes a movably mounted polishing member, a wafer holder, and a slurry dispenser. The multiple conditioning members may be independently movable with respect to one another and configured to contact the polishing member. Specifically, a conditioning member may be independently movable with respect to another conditioning member based on x-axis control, y-axis control, z-axis control, alignment, speed of rotation, direction of rotation, amount of pressure of conditioning member on polishing member.